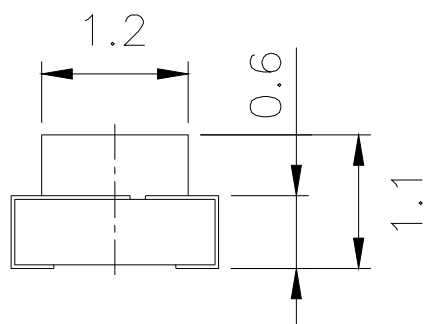
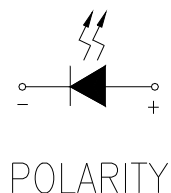
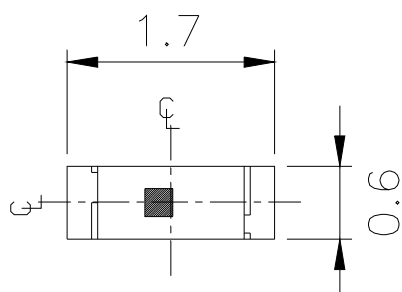
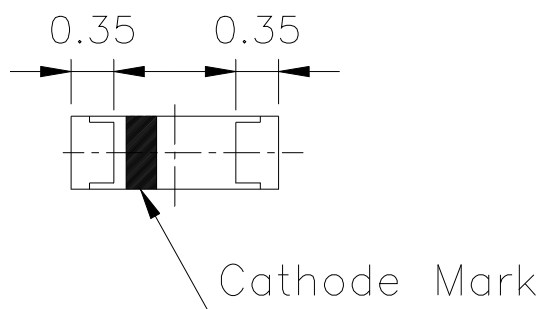
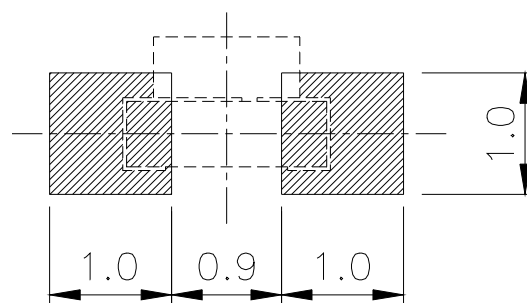


## Package Outline Dimensions



For Reflow Soldering (propose)



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Unit = mm

**27-21/GHC-YR2T1/3C**
**Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I <sub>FP</sub>	100	mA
Power Dissipation	P <sub>d</sub>	110	mW
Electrostatic Discharge(HBM)	ESD	150	V
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +90	°C
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260°C for 10sec. Hand Soldering : 350°C for 3 sec..	

**Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	140	-----	360	mcd	I <sub>F</sub> =20mA
Viewing Angle	2 θ 1/2	-----	130	-----	deg	
Peak Wavelength	λ <sub>p</sub>	-----	518	-----	nm	
Dominant Wavelength	λ <sub>d</sub>	520	-----	535	nm	
Spectrum Radiation Bandwidth	△ λ	-----	35	-----	nm	
Forward Voltage	V <sub>F</sub>	2.7	3.3	3.7	V	
Reverse Current	I <sub>R</sub>	-----	-----	50	μ A	V <sub>R</sub> =5V

**Notes:**

- 1.Tolerance of Luminous Intensity ±11%
- 2.Tolerance of Dominant Wavelength ±1nm

**27-21/GHC-YR2T1/3C**
**Bin Range Of Luminous Intensity**

Bin	Min	Max	Unit	Condition
R2	140	180	mcd	I <sub>F</sub> =20mA
S1	180	225		
S2	225	285		
T1	285	360		

**Bin Range Of Dom. Wavelength**

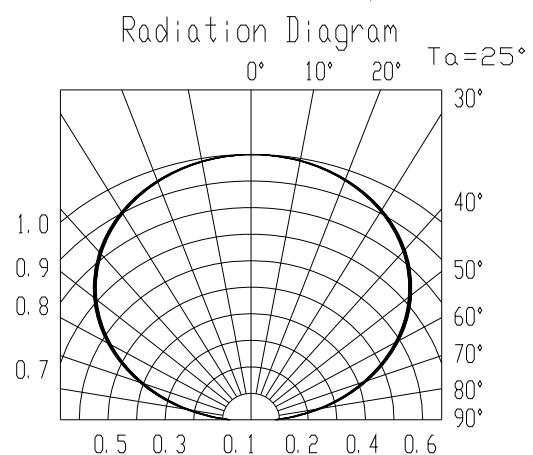
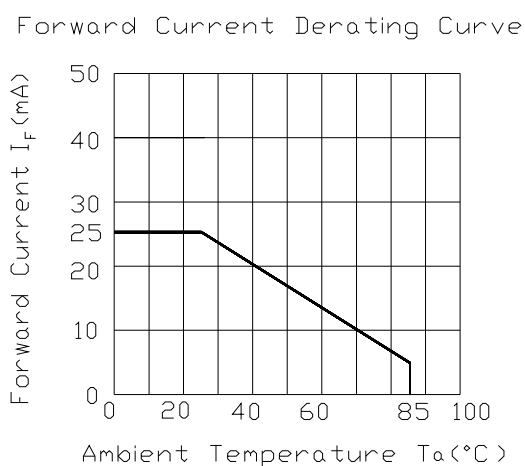
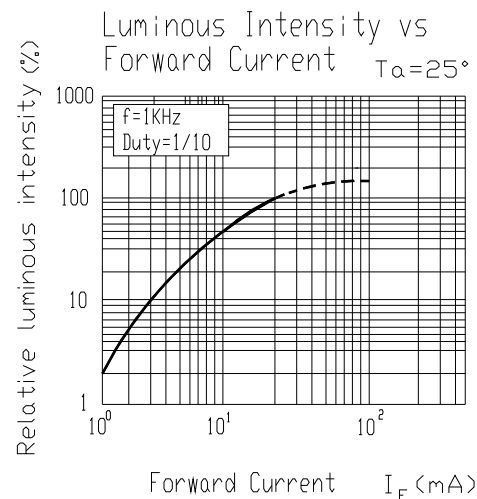
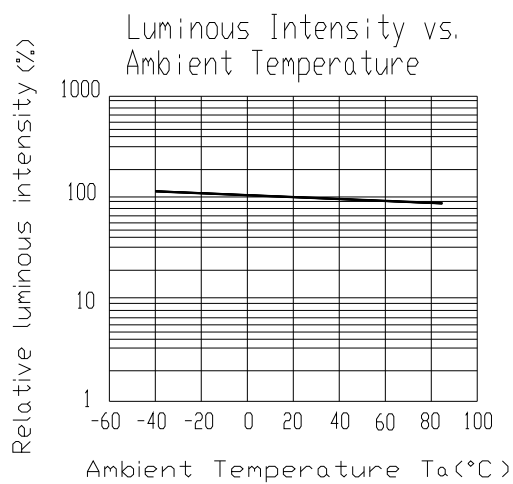
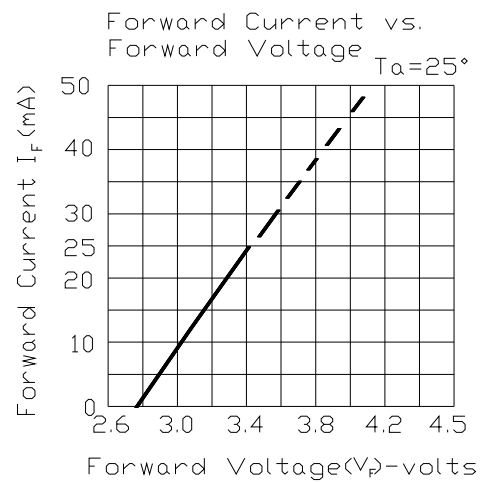
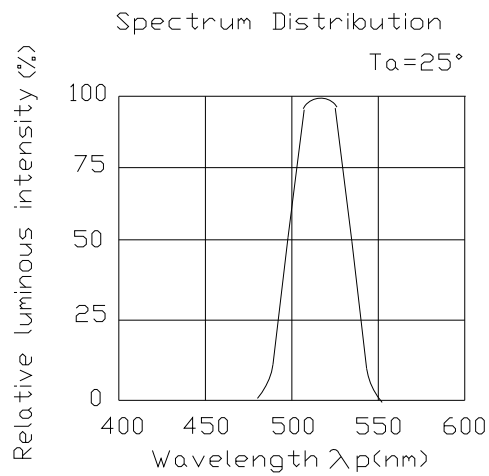
Groups	Bin	Min	Max	Unit	Condition
Y	X	520	525	nm	I <sub>F</sub> =20mA
	Y	525	530		
	Z	530	535		

**Notes:**

- 1.Tolerance of Luminous Intensity  $\pm 11\%$
- 2.Tolerance of Dominant Wavelength  $\pm 1\text{nm}$

**27-21/GHC-YR2T1/3C**

**Typical Electro-Optical Characteristics Curves**



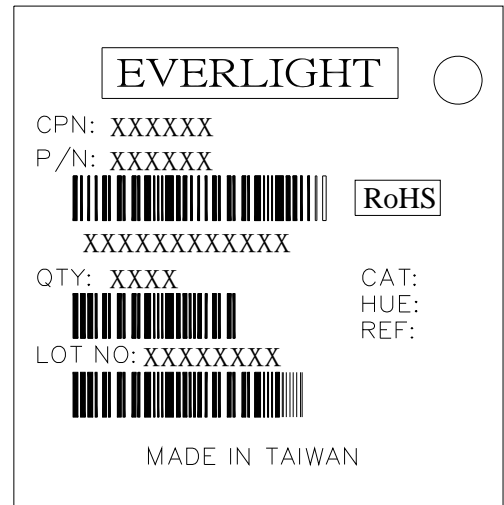
**27-21/GHC-YR2T1/3C**

**Label explanation**

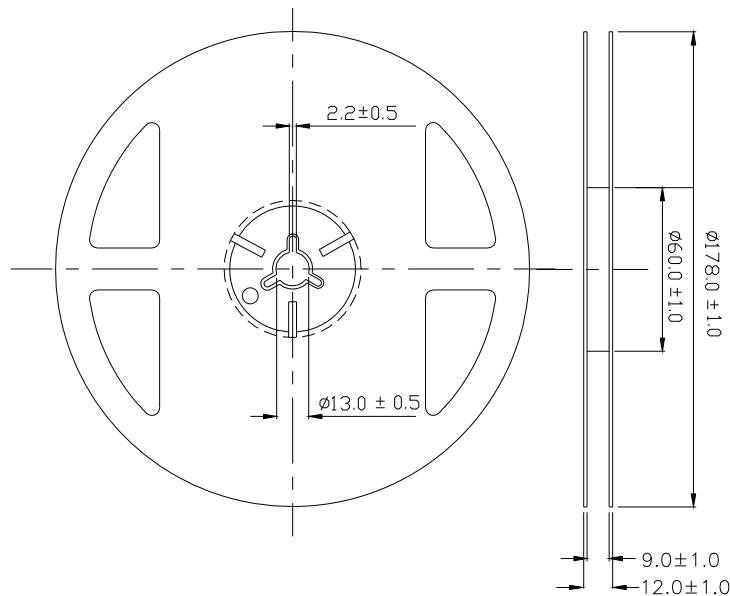
**CAT: Luminous Intensity Rank**

**HUE: Dom. Wavelength Rank**

**REF: Forward Voltage Rank**



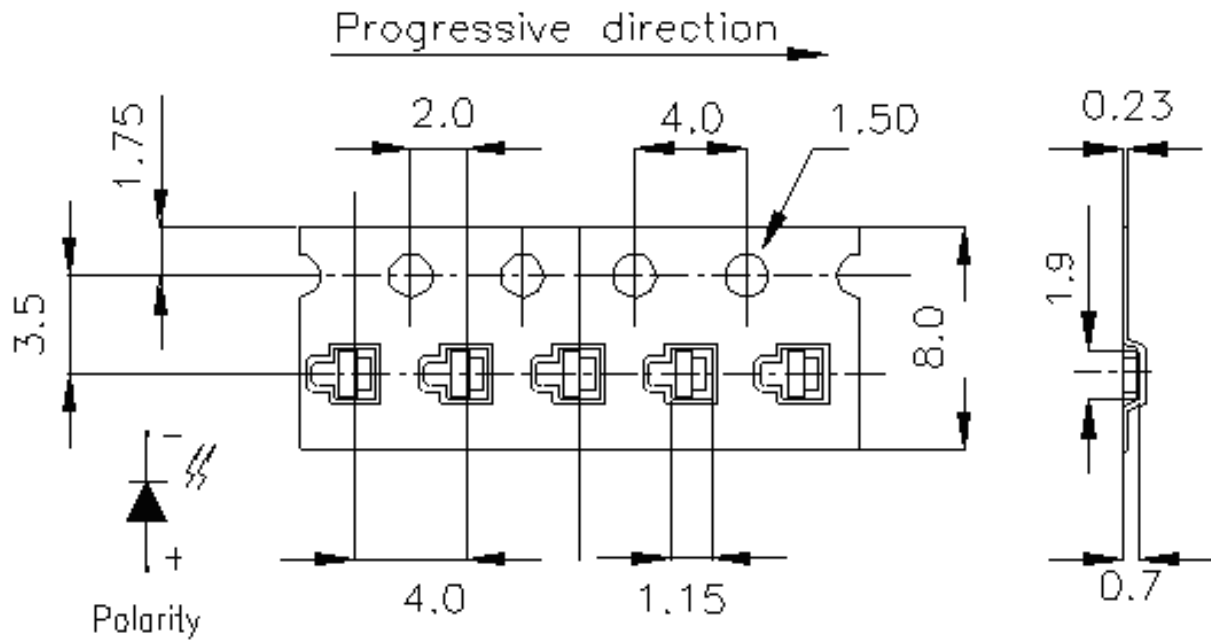
**Reel Dimensions**



**Note:** Tolerances Unless Dimension  $\pm 0.1\text{mm}$  ,Unit = mm

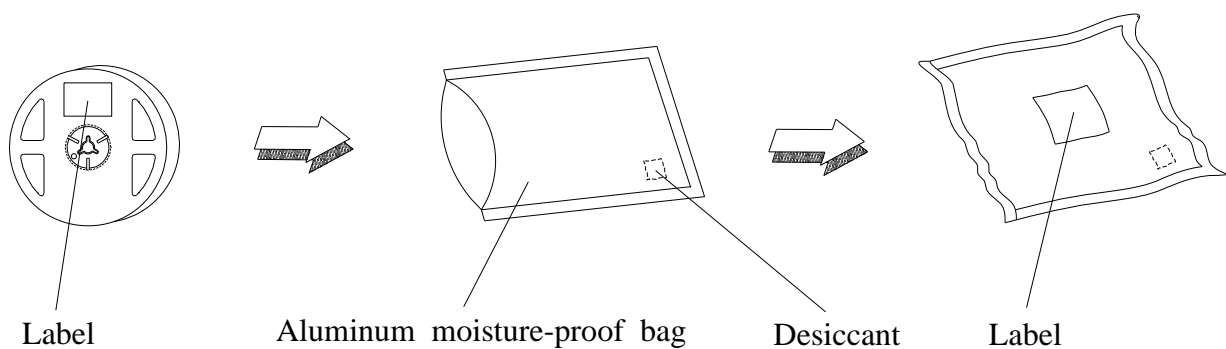
**27-21/GHC-YR2T1/3C**

**Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel**



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Unit = mm

**Moisture Resistant Packaging**



**Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I <sub>F</sub> = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

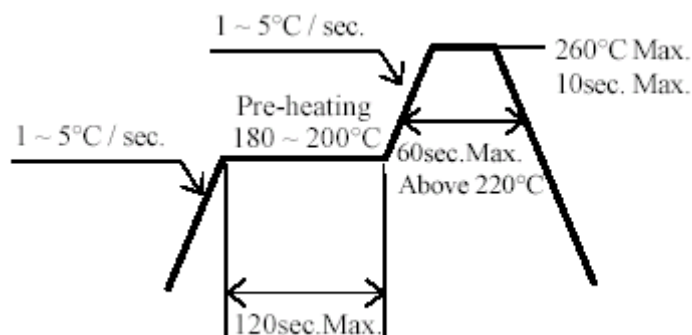
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment :  $60 \pm 5^{\circ}\text{C}$  for 24 hours.

### 3. Soldering Condition

#### 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

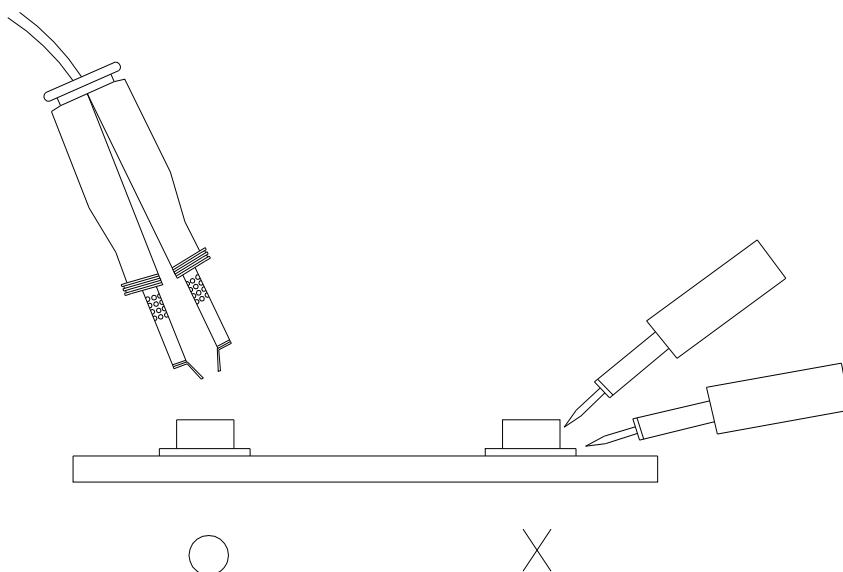
3.4 After soldering, do not warp the circuit board.

**27-21/GHC-YR2T1/3C****4. Soldering Iron**

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

**5.Repairing**

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

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